

**PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION**

**Part Number:** [0780658001](#)  
**Status:** **Active**  
**Description:** 1.00mm (.039") Pitch DDR2 DIMM Socket, Very Low Profile, Vertical, Press-fit, 1.8V Center Keys, 3.30mm (.130") Tail Length, Black Latches, 240 Circuits, 0.76µm (30µm) Gold(Au) Plating, Lead-free

**Documents:**

[3D Model](#) [Product Specification PS-78065-001 \(PDF\)](#)  
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)

**Agency Certification**

CSA LR19980  
 UL E29179

**General**

Product Family Memory Module Sockets  
 Series [78065](#)  
 Comments <LI>Latches in Black Color  
 Component Type Memory Module  
 JEDEC Outline MO-237  
 Product Name DDR2 DIMM

**Physical**

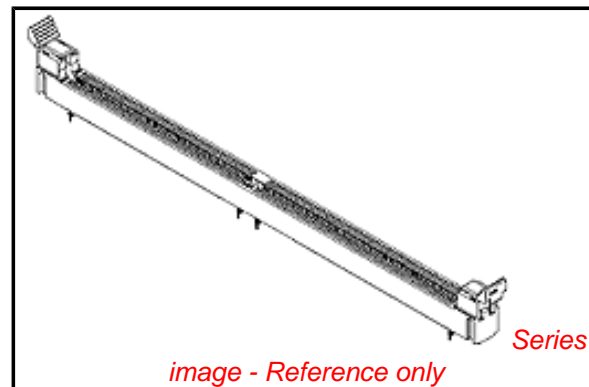
Circuits (Loaded) 240  
 Color - Resin Black  
 Durability (mating cycles max) 25  
 Entry Angle Vertical (Top Entry)  
 Flammability 94V-0  
 Keying to Mating Part Yes  
 Material - Metal Phosphor Bronze  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin  
 Material - Resin High Temperature Thermoplastic  
 PC Tail Length (in) 0.130 In  
 PC Tail Length (mm) 3.30 mm  
 PCB Locator No  
 PCB Retention Yes  
 PCB Thickness Recommended (in) 0.140 In  
 PCB Thickness Recommended (mm) 3.60 mm  
 Packaging Type Tray  
 Pitch - Mating Interface (in) 0.039 In  
 Pitch - Mating Interface (mm) 1.00 mm  
 Plating min: Mating (µin) 30  
 Plating min: Mating (µm) 0.76  
 Plating min: Termination (µin) 15.2  
 Plating min: Termination (µm) 0.38  
 Temperature Range - Operating -55°C to +85°C  
 Termination Interface: Style Through Hole - Compliant Pin

**Electrical**

Current - Maximum per Contact 0.5A  
 Voltage - Maximum 30V  
 Voltage Key 1.8V, Center

**Material Info**

**Reference - Drawing Numbers**



*image - Reference only*

**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC Contains SVHC: No**  
**Halogen-Free Status**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

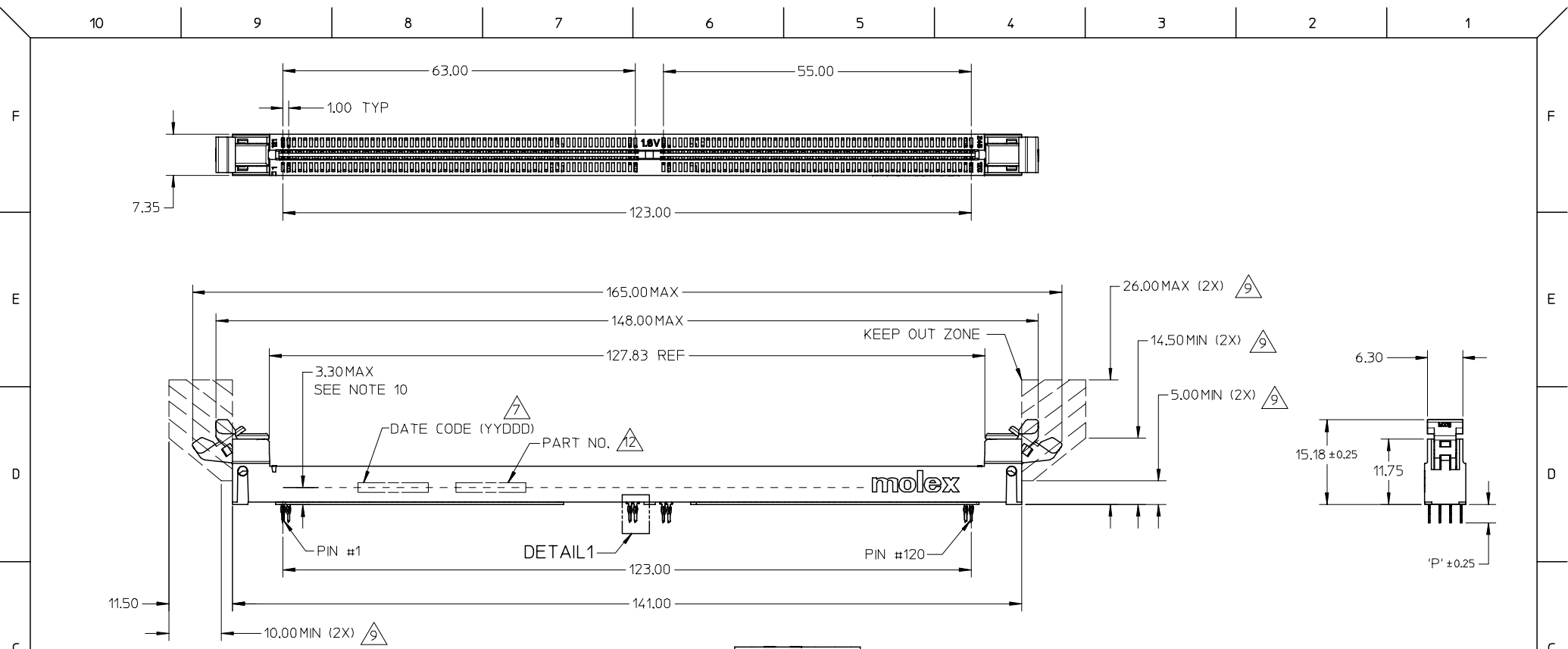
[78065Series](#)

**Mates With**

JEDEC MO-237 modules

This document was generated on 04/13/2010

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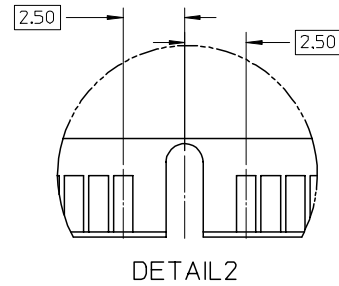
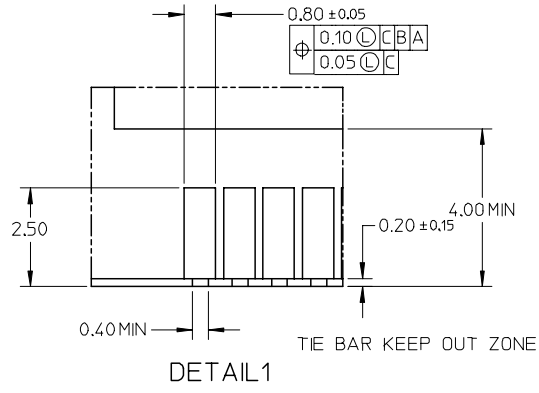
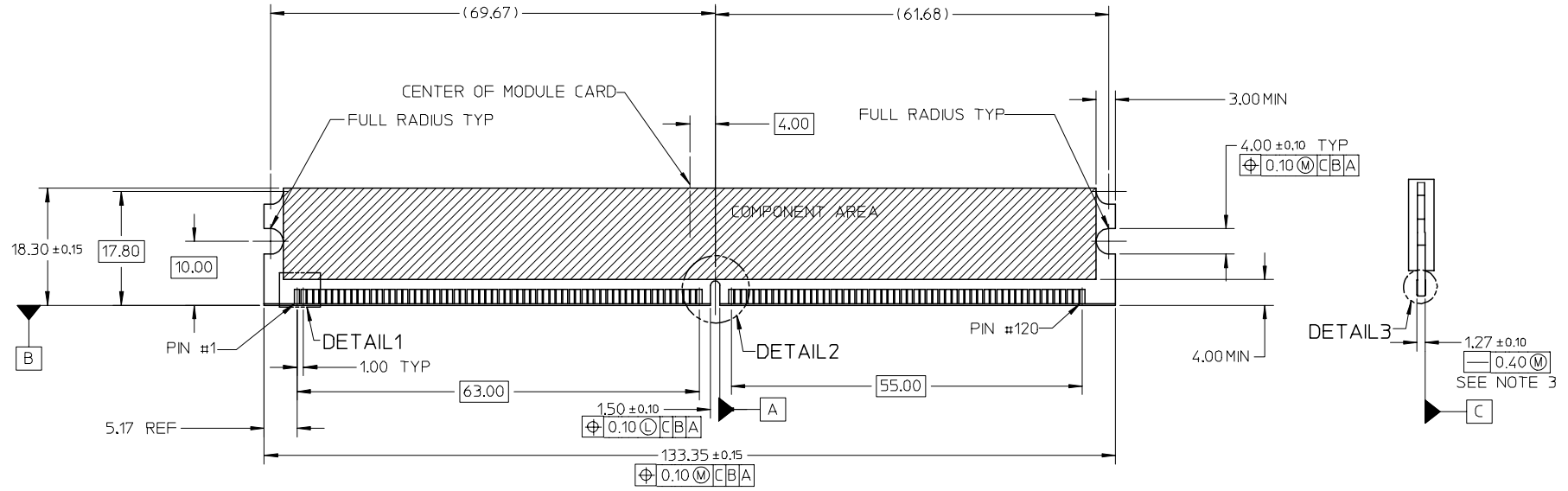


- NOTES:
- MATERIALS  
HOUSING - HIGH TEMP NYLON GLASS FILLED, UL 94V-0, COLOR - BLACK  
EJECTOR - HIGH TEMP NYLON 46, COLOR: BLACK  
TERMINAL - PHOSPHOR BRONZE
  - PLATING - SEE TABLE IN SHEET 4.
  - CARD SLOT ACCEPTS 1.27±0.10MM MODULE THICKNESS.
  - RECOMMENDED MODULE LAYOUT SHALL BE AS PER JEDEC MO-237.
  - REFER TO PRODUCT SPEC. PS-78065-100 FOR PERFORMANCE SPECIFICATIONS.
  - PRODUCT SHALL BE PACKED IN TRAY.
  - PRODUCT SHALL HAVE DATE CODE STAMPED ON SIDE OF HOUSING.
  - KEEP OUT AREA IS THE AREA WHERE THE CONNECTOR IS MOUNTED ONTO THE PCB WHICH DOES NOT INCLUDE THE LATCH.
  - KEEP OUT ZONE AS PER JEDEC S0-001.
  - DIMM MODULE SEATING PLANE FROM TOP OF PCB.
  - CONTACT MOLEX FOR AVAILABILITY OF PRODUCT OPTIONS.
  - PART NUMBER SHALL BE MARKED LEGIBLY AS 78065-\*\*\*\*.

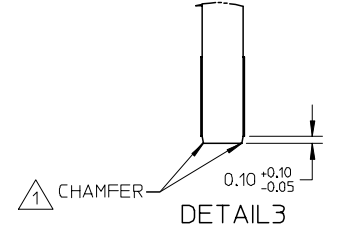
UPDATE M.C DWG EC NO: S2008-0319 DRWN:CMTEO CHKD:CCTEH APPR:SHLENI	2007/10/18 2007/10/19 2007/10/22	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
			4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.20 ± ---	1 PLACE ± --- ± ---	ANGULAR ± 5 °	DRAWN BY VMANICKAM	DATE 2006/04/11
A1	REV	DESCRIPTION	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE	APPROVED BY SRRAMESH	DATE 2006/06/22	MOLEX INCORPORATED	
					SIZE A3	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		DOCUMENT NO. SD-78065-001	SHEET NO. 1 OF 4

10 9 8 7 6 5 4 3 2 1

RECOMMENDED MODULE LAYOUT



KEY LOCATION	VOLTAGE
CENTER	1.8V



NOTES:  
 CHAMFER MODULE CARD USED FOR TESTS ARE WITH 0.10MM CHAMFER.

REV	DESCRIPTION
A1	UPDATE M.C DWG
	EC NO: S2008-0319
	DRWN:CMTEO 2007/10/18
	CHKD:CCTEH 2007/10/19
	APPR:SHLENI 2007/10/22

QUALITY SYMBOLS	VALUE
▽=0	
∇=0	

GENERAL TOLERANCES (UNLESS SPECIFIED)	
mm	INCH
4 PLACES ± ---	± ---
3 PLACES ± ---	± ---
2 PLACES ± 0.20	± ---
1 PLACE ± ---	± ---
ANGULAR ± 5 °	

DIMENSION STYLE	
MM ONLY	
DRAWN BY	DATE
VMANICKAM	2006/04/11
CHECKED BY	DATE
SHLENI	2006/06/22
APPROVED BY	DATE
SRRAMESH	2006/06/22
MATERIAL NO.	
SEE TABLE	

SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
NTS	METRIC	THIRD ANGLE PROJECTION
TITLE		
VLP DDR2 DIMM, 1MM PITCH		
240 CKTS, VERT. PRESSFIT		
MOLEX INCORPORATED		SHEET NO.
DOCUMENT NO. SD-78065-001		2 OF 4

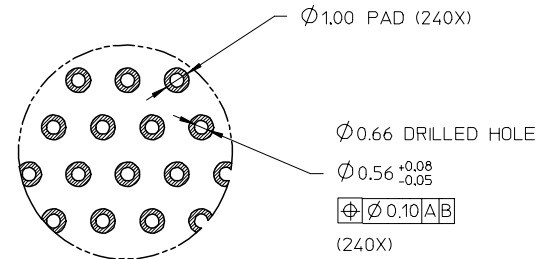
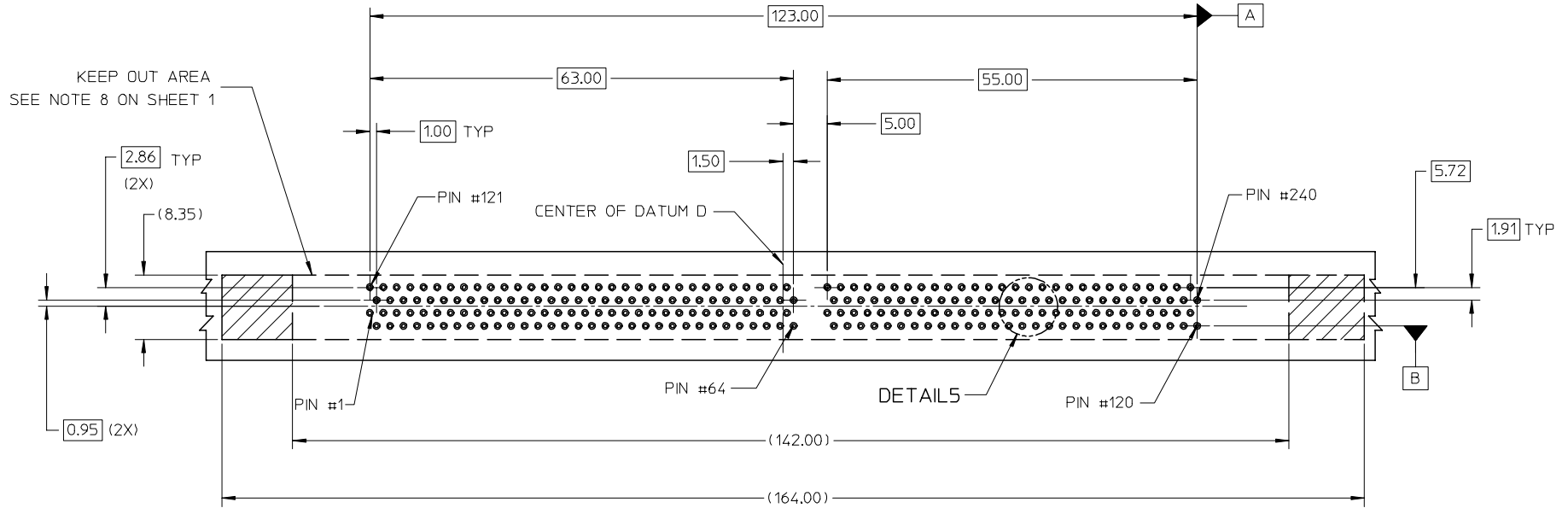
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9 8 7 6 5 4 3 2 1

10 9 8 7 6 5 4 3 2 1

F  
E  
D  
C  
B  
A

(SEE RECOMMENDED THICKNESS IN TABLE)  
RECOMMEND PCB LAYOUT  
CONNECTOR SIDE



DETAIL5

UPDATE M.C DWG EC NO: S2008-0319 DRWN:CMTEO 2007/10/18 CHKD:CCTEH 2007/10/19 APPR:SHLENI 2007/10/22	QUALITY SYMBOLS ▽=0 ▽C=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		4 PLACES ± ---    ± --- 3 PLACES ± ---    ± --- 2 PLACES ± 0.20    ± --- 1 PLACE ± ---    ± ---	mm    INCH	DRAWN BY VMANICKAM	DATE 2006/04/11	TITLE VLP DDR2 DIMM, 1MM PITCH 240 CKTS, VERT. PRESSFIT			
		ANGULAR ± 5 °		CHECKED BY SHLENI	DATE 2006/06/22	MOLEX INCORPORATED			
	A1	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		APPROVED BY SRRAMESH	DATE 2006/06/22	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-78065-001	SHEET NO. 3 OF 4	

9 8 7 6 5 4 3 2 1

TIN OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	LATCH COLOR
78065-8001	CENTER	1.8V	3.30	3.60	0.76µM/30µM MIN GOLD OVER 1.27µM/50µM MIN NICKEL UNDERPLATE	0.38-1.52µM/15-60µM TIN OVER 1.27µM/50µM MIN NICKEL UNDERPLATE	BLACK
78065-8002			4.20	4.57			

TIN/LEAD OPTION

PART NO.	VOLTAGE KEY POS.	VOLTAGE	DIM 'P'	RECOMMENDED PCB THICKNESS	CONTACT AREA PLATING OPTION	SOLDERTAIL PLATING OPTION	LATCH COLOR
78065-8101	CENTER	1.8V	3.30	3.60	0.76µM/30µM MIN GOLD OVER 1.27µM/50µM MIN NICKEL UNDERPLATE	0.38-1.52µM/15-60µM TIN/LEAD OVER 1.27µM/50µM MIN NICKEL UNDERPLATE	BLACK
78065-8102			4.20	4.57			

UPDATE M.C DWG EC NO: S2008-0319 DRWN:CMTEO CHKD:CCTEH APPR:SHLENI	2007/10/18 2007/10/19 2007/10/22	QUALITY SYMBOLS ▽=0 ▽=0	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION		
			4 PLACES ± --- ± ---	mm INCH	DRAWN BY VMANICKAM	DATE 2006/04/11	TITLE VLP DDR2 DIMM, 1MM PITCH 240 CKTS, VERT. PRESSFIT				
			3 PLACES ± --- ± ---		CHECKED BY SHLENI	DATE 2006/06/22					
			2 PLACES ± 0.20 ± ---		APPROVED BY SRRAMESH	DATE 2006/06/22	MOLEX INCORPORATED				
		1 PLACE ± --- ± ---		MATERIAL NO.		DOCUMENT NO.					SHEET NO.
A1		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE TABLE		SD-78065-001		4 OF 4		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		